

enetSEAL+

TE Internal #: 2325102-7

PCB Mount Header, Vertical, Wire-to-Board, 2 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Unplated, Through Hole - Solder,

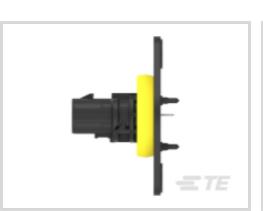
Sealable, Signal

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Connectors > PCB Connectors > PCB Headers & Receptacles











Connector System: Wire-to-Board

Number of Positions: 2

Centerline (Pitch): 2.54 mm [.1 in]

Sealable: Yes

PCB Mount Orientation: Vertical

Features

Product Type Features

Hybrid Header	No
Connector Shape	Rectangular
PCB Connector Assembly Type	PCB Mount Header
Header Type	Fully Shrouded
Connector System	Wire-to-Board
Sealable	Yes
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Sections	1
Number of Positions	2
PCB Mount Orientation	Vertical
Number of Rows	1
Electrical Characteristics	

33 VAC

Operating Voltage



Body Features

Primary Product Color	Black
Connector Code	A

Contact Features

Contact Size	8mm
Contact Type	Tab
Mating Tab Width	1.2 mm[.047 in]
Mating Tab Thickness	.6 mm[.024 in]
Contact Mating Area Plating Material	Unplated
Contact Current Rating (Max)	10 A

Termination Features

Mechanical Attachment

Mating Alignment	With
Connector Mounting Type	Board Mount

Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
Centernine (Fitch)	2.54 11111[.1 111]

Usage Conditions

Operating Temperature Range	-40 - 125 °C[-40 - 257 °F]

Operation/Application

Shielded	No
Circuit Application	Signal

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC



Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC
	Free

Solder Process Capability

Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2325102-7_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2325102-7_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2325102-7_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Product Specifications

Application Specification

English

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